

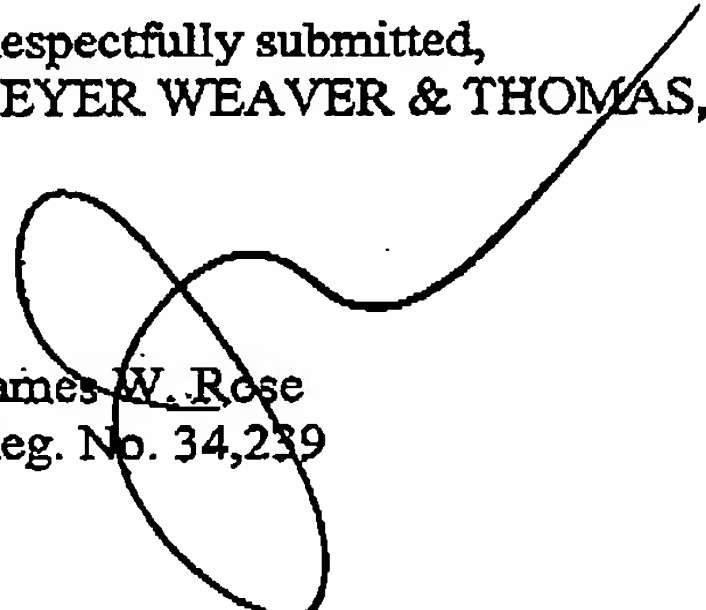
DEC 14 2006**REMARKS**

The Attorney for the Applicants' wishes to thank the Examiner for the telephone interview on December 13, 2006. During the interview, the Examiner indicated that the application would be allowable by amending the claims to include: (i) a reflowable underfill material; and (ii) the reflow underfill material is configured to reflow and fill in the gap between the chip and a substrate when the solder balls are reflowed during mounting of the clip onto the substrate. In contrast, the material 30 in Kinsman is an encapsulant that hermetically seals the integrated circuitry on the die.

Paragraph [0026] of Kinsman specifically states that the encapsulant material 30 forms a "hermetic seal" over the integrated circuitry 18 on the active surface 14 of the substrate. Since the stated purpose of the encapsulant 30 is to form a hermetic seal over the circuitry, Kinsman actually teaches away from the present invention. If the material 30 were to reflow like the underfill material of the present invention, there is a strong possibility that the hermetic seal would be broken, exposing the underlying circuitry 18.

The Applicants' believe that all pending claims are allowable and respectfully request a Notice of Allowance for this application from the Examiner. In the event the case is not allowable, it is requested that the Examiner call the undersigned for another telephone interview.

Respectfully submitted,
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